

FLEX STACK

(1.00 mm) .0394"

**MW SERIES**

SMT MICRO BOARD HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MW

Insulator Material:

Top: Black LCP
Bottom: Natural LCP

Terminal Material:

Phosphor Bronze

Operating Temp Range:

-55 °C to +125 °C

Plating:

Au over 50 μ" (1.27 μm) Ni

RoHS Compliant:

Yes

Mates with:
CLM, MLE

ALSO AVAILABLE (MOQ Required)

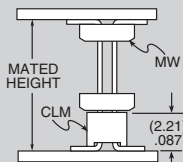
- End shrouds
- End shrouds with guide posts



APPLICATIONS

EXAMPLES		
LEAD STYLE		MATED HEIGHT*
MW	CLM	
-163-065	-02	(6.35) .250
-233-065		(8.13) .320

*Processing conditions will affect mated height.



Available with optional end shrouds and pick-and-place pads

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-30)
(0.15 mm) .006" max (31-50)*

*(.004" stencil solution

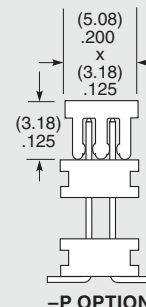
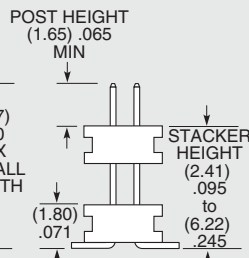
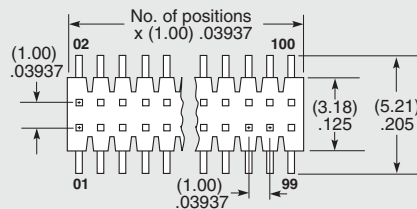
may be available; contact ipg@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MW	NO. PINS PER ROW	03	PLATING OPTION	D	STACKER HEIGHT	POST HEIGHT	OPTION
	02 thru 50		-G		-“XXX” = Stacker Height (in inches) (2.41 mm) .095" to (6.22 mm) .245"	-“XXX” = Post Height (in inches) (1.65 mm) .065" minimum Example: -065 = (1.65 mm) .065"	-A = Alignment Pin (5 positions minimum) Metal or plastic at Samtec's discretion -P = Pick & Place Pad (7 positions minimum) -TR = Tape & Reel



Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.